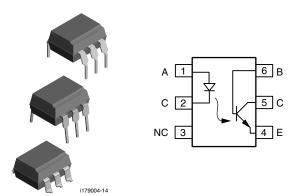


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Vishay Semiconductors

Optocoupler, Phototransistor Output, with Base Connection



DESCRIPTION

This datasheet presents five families of Vishay industry standard single channel phototransistor couplers. These families include the 4N35, 4N36, 4N37, 4N38 couplers.

Each optocoupler consists of gallium arsenide infrared LED and a silicon NPN phototransistor.

These couplers are Underwriters Laboratories (UL) listed to comply with a 5000 V_{RMS} isolation test voltage.

This isolation performance is accomplished through Vishay double molding isolation manufacturing process. Comliance to DIN EN 60747-5-5 partial discharge isolation specification is available for these families by ordering option 1.

These isolation processes and the Vishay ISO9001 quality program results in the highest isolation performance available for a commecial plastic phototransistor optocoupler.

The devices are available in lead formed configuration suitable for surface mounting and are available either on tape and reel, or in standard tube shipping containers.

Note

For additional design information see application note 45 normalized curves

FEATURES

- Isolation test voltage 5000 V_{RMS}
- · Interfaces with common logic families
- Input-output coupling capacitance < 0.5 pF
- · Industry standard dual-in-line 6 pin package
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC



APPLICATIONS

- · AC mains detection
- · Reed relay driving
- Switch mode power supply feedback
- Telephone ring detection
- Logic ground isolation
- · Logic coupling with high frequency noise rejection

AGENCY APPROVALS

- UL file no. E52744 (pending)
- cUL tested to CSA 22.2 bulletin 5A
- DIN EN 60747-5-2 (VDE 0884)/DIN EN 60747-5-5 (pending), available with option 1
- BSI: EN 60065, EN 60950-1
- FIMKO
- CQC

normalized curves								
ORDERING INFORMATIO	N							
4 N 3 PART NUMBER	x - X	0 #	# T TAPE AND REEL	DIP-6 Option 6 62 mm 10.16 mm ption 7 Option 9 8 mm typ.				
AGENCY CERTIFIED/PACKAGE	CTR (%)							
AGENOT GENTINED/T AGRAGE		20 mA						
UL, cUL, BSI, FIMKO		≥ 100		≥ 20				
DIP-6	4N35-X000	4N36-X000	4N37-X000	4N38				
DIP-6, 400 mil, option 6	4N35-X006	-	4N37-X006	-				
SMD-6, option 7	4N35-X007T ⁽¹⁾	4N36-X007	4N37-X007	4N38-X007T ⁽¹⁾				
SMD-6, option 9	4N35-X009T (1)	4N36-X009T (1)	4N37-X009	4N38-X009T				
VDE, UL, cUL, BSI, FIMKO	≥100 ≥20							
DIP-6	4N35-X001	-	4N37-X001	-				
DIP-6, 400 mil, option 6	4N35-X016	-	-	-				
SMD-6, option 7	4N35-X017T ⁽¹⁾	-	-	-				

SMD-6, option 9

Additional options may be possible, please contact sales office.

4N35-X019T

(1) Also available in tubes; do not put T on end.



PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
INPUT			<u> </u>	
Reverse voltage		V_{R}	6	V
Forward current		I _F	60	mA
Surge current	t ≤ 10 μs	I _{FSM}	2.5	Α
Power dissipation		P _{diss}	70	mW
ОИТРИТ	<u>.</u>			
Collector emitter breakdown voltage		V _{CEO}	70	V
Emitter base breakdown voltage		V _{EBO}	7	V
Collector current		I _C	50	mA
Collector peak current	$t_p/T = 0.5, t_p \le 10 \text{ ms}$	I _{CM}	100	mA
Output power dissipation		P _{diss}	150	mW
COUPLER				
Isolation test voltage	t = 1 s	V _{ISO}	5000	V_{RMS}
Creepage distance			≥7	mm
Clearance distance			≥7	mm
Isolation thickness between emitter and detector			≥ 0.4	mm
Comparative tracking index	DIN IEC 112/VDE 0303, part 1		≥ 175	
la clation registers o	V _{IO} = 500 V, T _{amb} = 25 °C	R _{IO}	≥ 10 ¹²	Ω
Isolation resistance	V _{IO} = 500 V, T _{amb} = 100 °C	R _{IO}	≥ 10 ¹¹	Ω
Storage temperature		T _{stg}	- 55 to + 150	°C
Operating temperature		T _{amb}	- 55 to + 100	°C
Soldering temperature (1)	2 mm from case, ≤ 10 s	T _{sld}	260	°C

Notes

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not
 implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute
 maximum ratings for extended periods of the time can adversely affect reliability.
- (1) Refer to reflow profile for soldering conditions for surface mounted devices (SMD). Refer to wave profile for soldering condditions for through hole devices (DIP).

ELECTRICAL CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)									
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT		
INPUT									
F	$I_F = 10 \text{ mA}$		V_{F}		1.2	1.5	٧		
Forward voltage (1)	$I_F = 10 \text{ mA}, T_{amb} = -55 ^{\circ}\text{C}$		V_{F}	0.9	1.3	1.7	V		
Reverse current (1)	V _R = 6 V		I _R		0.1	10	μA		
Capacitance	$V_R = 0 V, f = 1 MHz$		Co		25		pF		
OUTPUT									
	I _C = 1 mA	4N35	BV _{CEO}	30			V		
Collector emitter breakdown		4N36	BV _{CEO}	30			V		
voltage ⁽¹⁾		4N37	BV _{CEO}	30			V		
		4N38	BV _{CEO}	80			V		
Emitter collector breakdown voltage ⁽¹⁾	I _E = 100 μA		BV _{ECO}	7			٧		
Collector base breakdown voltage ⁽¹⁾		4N35	BV _{CBO}	70			V		
	I _C = 100 μA, I _B = 1 μA	4N36	BV _{CBO}	70			V		
		4N37	BV _{CBO}	70			V		
		4N38	BV _{CBO}	80			V		

ELECTRICAL CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)									
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT		
OUTPUT									
	$V_{CE} = 10 \text{ V}, I_F = 0$	4N35	I _{CEO}		5	50	nA		
		4N36	I _{CEO}		5	50	nA		
	$V_{CE} = 10 \text{ V}, I_F = 0$	4N37	I _{CEO}		5	50	nA		
	$V_{CE} = 60 \text{ V}, I_F = 0$	4N38	I _{CEO}			50	nA		
Collector emitter leakage current (1)	V _{CE} = 30 V, I _F = 0, T _{amb} = 100 °C	4N35	I _{CEO}			500	μΑ		
		4N36	I _{CEO}			500	μA		
		4N37	I _{CEO}			500	μΑ		
	$V_{CE} = 60 \text{ V}, I_{F} = 0,$ $T_{amb} = 100 ^{\circ}\text{C}$	4N38	I _{CEO}		6		μΑ		
Collector emitter capacitance	$V_{CE} = 0$		C _{CE}		6		pF		
coupler									
Resistance, input output (1)	$V_{1O} = 500 \text{ V}$		R _{IO}	10 ¹¹			Ω		
Capacitance, input output	f = 1 MHz		C _{IO}	•	0.5		pF		

Notes

⁽¹⁾ Indicates JEDEC registered value.

CURRENT TRANSFER RATIO (T _{amb} = 25 °C, unless otherwise specified)							
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
I _O /I _F ⁽¹⁾		4N35	CTR _{DC}	100			%
	$V_{CE} = 10 \text{ V}, I_F = 10 \text{ mA}$	4N36	CTR _{DC}	100			%
		4N37	CTR _{DC}	100	100		%
	$V_{CE} = 10 \text{ V}, I_F = 20 \text{ mA}$	4N38	CTR _{DC}	20			%
		4N35	CTR _{DC}	40	50		%
	$V_{CE} = 10 \text{ V}, I_F = 10 \text{ mA},$	4N36	CTR _{DC}	40	50		%
	$V_{CE} = 10 \text{ V}, I_F = 10 \text{ mA},$ $T_A = -55 \text{ °C to} + 100 \text{ °C}$	4N37	CTR _{DC}	40	50		%
		4N38	CTR _{DC}		30		%

Note

⁽¹⁾ Indicates JEDEC registered values.

SWITCHING CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)							
PARAMETER	TEST CONDITION SYMBOL MIN. TYP. MAX. UNI					UNIT	
Turn-on time (1)	V_{CC} = 5 V, I_C = 2 mA, R_L = 100 Ω	t _{on}		10		μs	
Turn-off time (1)	V_{CC} = 5 V, I_C = 2 mA, R_L = 100 Ω	t _{off}		10		μs	

Note

(1) Indicates JEDEC registered values.

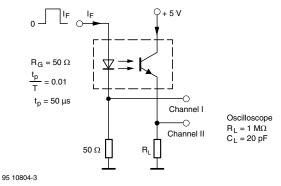


Fig. 1 - Test Circuit, Non-Saturated Operation

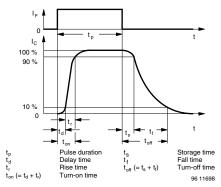


Fig. 2 - Switching Times

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering
evaluation. Typical values are for information only and are not part of the testing requirements.

TYPICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

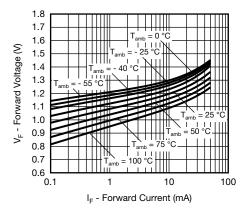


Fig. 3 - Forward Voltage vs. Forward Current

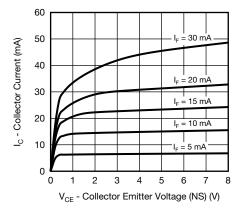


Fig. 4 - Collector Current vs. Collector Emitter Voltage (NS)

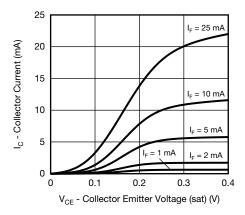


Fig. 5 - Collector Current vs. Collector Emitter Voltage (sat)

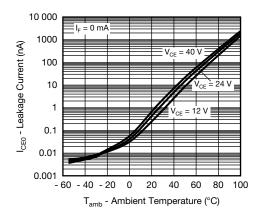


Fig. 6 - Leakage Current vs. Ambient Temperature

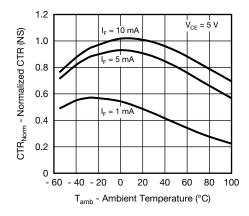


Fig. 7 - Normalized CTR (NS) vs. Ambient Temperature

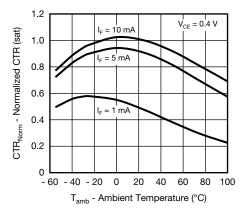


Fig. 8 - Normalized CTR (sat) vs. Ambient Temperature

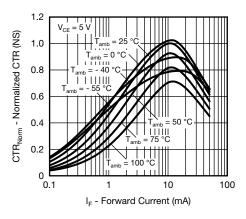


Fig. 9 - Normalized CTR (NS) vs. Forward Current

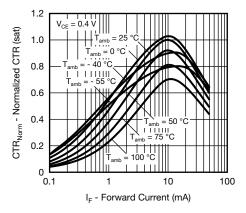


Fig. 10 - Normalized CTR (sat) vs. Forward Current

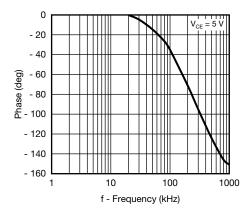


Fig. 11 - CTR Frequency vs. Phase Angle

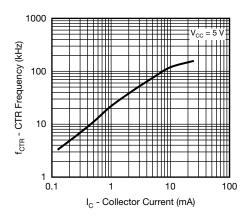


Fig. 12 - CTR Frequency vs. Collector Current

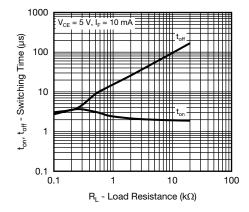
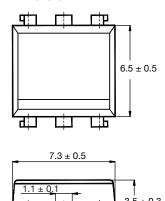
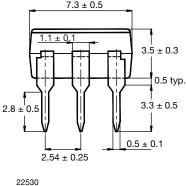
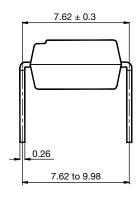


Fig. 13 - Switching Time vs. Load Resistance

PACKAGE DIMENSIONS in millimeters



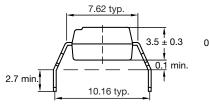


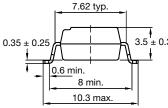


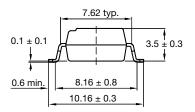
Option 6

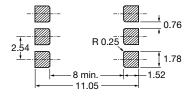
Option 7

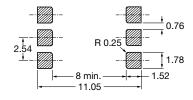
Option 9



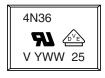








20802-34 PACKAGE MARKING



Notes

- · VDE logo is only marked on option 1 parts. Option information is not marked on the part.
- Tape and reel suffix (T) is not part of the package marking.



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Vishay

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Revision: 02-Oct-12 Document Number: 91000